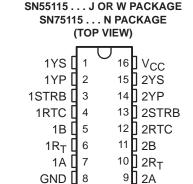
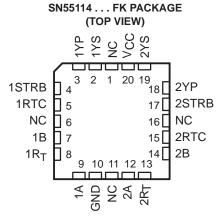
- Choice of Open-Collector or Active Pullup (Totem-Pole) Outputs
- Single 5-V Supply
- Differential Line Operation
- Dual-Channel Operation
- TTL Compatible
- ±15-V Common-Mode Input Voltage Range
- Optional-Use Built-In 130-Ω Line-Terminating Resistor
- Individual Frequency-Response Controls
- Individual Channel Strobes
- Designed for Use With SN55113, SN75113, SN55114, and SN75114 Drivers
- Designed to Be Interchangeable With National DS9615 Line Receivers

description

The SN55115 and SN75115 dual differential line receivers are designed to sense small differential signals in the presence of large common-mode noise. These devices give TTL-compatible output signals as a function of the differential input voltage. The open-collector output configuration permits the wire-ANDing of similar TTL outputs (such as SN5401/SN7401) or other SN55115/SN75115 line receivers. This permits a level of logic to be implemented without extra delay.





NC - No internal connection

The output stages are similar to TTL totem-pole outputs, but with sink outputs, 1YS and 2YS, and the corresponding active pullup terminals, 1YP and 2YP, available on adjacent package pins. The frequency response and noise immunity may be provided by a single external capacitor. A strobe input is provided for each channel. With the strobe in the low level, the receiver is disabled and the outputs are forced to a high level.

The SN55115 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN75115 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

STRB	DIFF INPUT (A AND B)	OUTPUT (YP AND YS TIED TOGETHER)
L	Х	Н
Н	L	Н
Н	Н	L

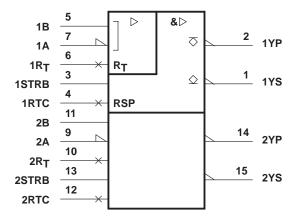
 $H = V_1 \ge V_{IH}$ min or V_{ID} more positive than V_{T+} max $L = V_1 \le V_{IL}$ max or V_{ID} more negative than V_{T-} max X = irrelevant



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

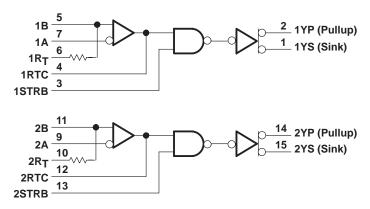


logic symbol†

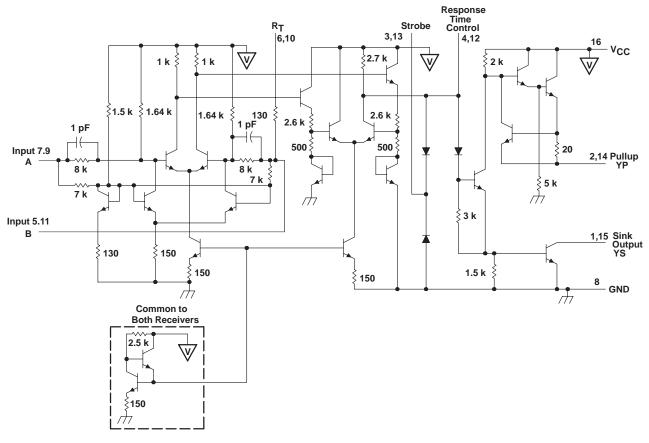


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



schematic (each receiver)



Resistor values are nominal and in ohms.

Pin numbers shown are for the J, N, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage V _I (A, B, and R _T)	
Input voltage V _I (STRB)	
Off-state voltage applied to open-collector outputs	14 V
Continuous total power dissipation	See Dissipation Rating Table
Storage temperature range, T _{stq}	–65°C to 150°C
Case temperature for 60 seconds: FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J or W package	ge 300°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential input voltage, are with respect to network ground terminal.



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DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
FK [†]	1375 mW	11.0 mW/°C	880 mW	275 mW
J†	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	_
wt	1000 mW	8.0 mW/°C	640 mW	200 mW

[†] In the FK, J, and W packages, SN55115 chips are either silver glass or alloy mounted. SN75115 chips are glass mounted.

recommended operating conditions

		SN55115			SN75115				
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT		
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V		
High-level input voltage at STRB, V _{IH}	2.4			2.4			V		
Low-level input voltage at STRB, V _{IL}			0.4			0.4	V		
High-level output current, IOH			-5			-5	mA		
Low-level output current, IOL			15			15	mA		
Operating free-air temperature, TA	-55		125	0		70	°C		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	750	r ooupitionst			SN55115		5	N75115		LINUT
	PARAMETER	IES	r conditions†		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
V _{IT+} §	Positive-going threshold voltage	V _O = 0 .4 V,	I _{OL} = 15 mA,	VIC = 0			500			500	mV
V _{IT} _§	Negative-going threshold voltage	V _O = 2 .4 V,	$I_{OH} = -5 \text{ mA},$	VIC = 0	-500¶			-500¶			mV
VICR	Common-mode input voltage range	V _{ID} = ±1 V			+15 to -15	+24 to -19		+15 to -15	+24 to -19		٧
			0.5.1/	$T_A = MIN$	2.2			2.4			
Vон	High-level ouput voltage	$V_{CC} = MIN$, $I_{OH} = -5 \text{ mA}$	$V_{ID} = -0.5 V$,	$T_A = 25^{\circ}C$	2.4	3.4		2.4	3.4		V
		011		$T_A = MAX$	2.4			2.4			
VOL	Low-level output voltage	$V_{CC} = MIN,$ $I_{OL} = 15 \text{ mA}$	$V_{ID} = -0.5 V$,			0.22	0.4		0.22	0.45	V
			.,	$T_A = MIN$			-0.9			-0.9	
I _{IL}	Low-level input current	V _{CC} = MAX, Other input at 5.5	$V_{I} = 0.4 \text{ V},$	$T_A = 25^{\circ}C$		-0.5	-0.7		-0.5	-0.7	mA
				$T_A = MAX$			-0.7			-0.7	
Ish	High-level strobe	V _{CC} = MIN,	$V_{ID} = -0.5 V$,	T _A = 25°C		-	2			5	μΑ
-311	current	V _{strobe} = 4.5 V		$T_A = MAX$			5			10	
I _{SL}	Low-level strobe current	$V_{CC} = MAX,$ $V_{strobe} = 0.4 V$	$V_{ID} = 0.5 V,$	T _A = 25°C		-1.15	-2.4		-1.15	-2.4	mA
I(RTC)	Response-time- control current	$V_{CC} = MAX,$ $V_{RC} = 0$	$V_{ID} = 0.5 V,$	T _A = 25°C	-1.2	-3.4		-1.2	-3.4		mA
		V _{CC} = MIN,	V _{OH} = 12 V,	T _A = 25°C			100				
I _O (off)	Off-state open-collector	$V_{ID} = -4.5 \text{ V}$	_	$T_A = MAX$			200				μΑ
10(011)	output current	V _{CC} = MIN,	$V_{OH} = 5.25 \text{ V},$	$T_A = 25^{\circ}C$						100	μΛ
		$V_{ID} = -4.75 \text{ V}$		$T_A = MAX$						200	
R _T	Line-terminating resistance	V _{CC} = 5 V		T _A = 25°C	77	130	167	74	130	179	Ω
los	Supply-circuit output current#	$V_{CC} = MAX,$ $V_{O} = 0$	$V_{ID} = -0.5 V,$	T _A = 25°C	-15	-40	-80	-14	-40	-100	mA
Icc	Supply current (both receivers)	$V_{CC} = MAX,$ $V_{IC} = 0$	$V_{ID} = 0.5 V,$	T _A = 25°C		32	50		32	50	mA

[†] Unless otherwise noted, V_{Strobe} = 2.4 V. All parameters with the exception of off-state open-collector output current are measured with the active pullup connected to the sink output.



[‡] All typical values are at $V_{CC} = 5$ V, $T_A = 25$ °C, and $V_{IC} = 0$.

[§] Differential voltages are at the B input terminal with respect to the A input terminal.

The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

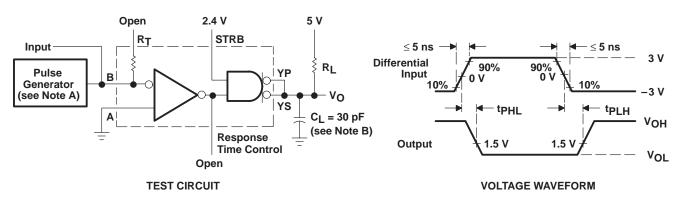
[#]Only one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second.

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switching characteristics, V_{CC} = 5 V, C_L = 30 pF, T_A = 25°C

	PARAMETER		TEST CONDITIONS -			SN55115			SN75115		
	FARAMETER	TEST CON	ADITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
^t PLH	Propagation delay time, low-to-high level output	$R_L = 3.9 \text{ k}\Omega$,	See Figure 1		18	50		18	75	ns	
tPHL	Propagation delay time, high-to-low level output	R _L = 390 Ω,	See Figure 1		20	50		20	75	ns	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: Z_O = 50 Ω , PRR \leq 500 kHz, $t_W \leq$ 100 ns, duty cycle = 50%.

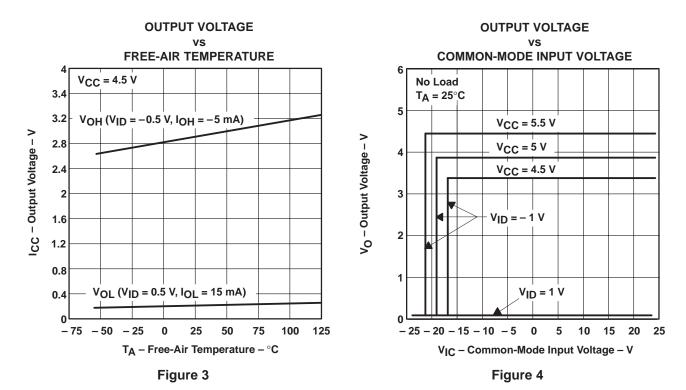
B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS[†]

INPUT CURRENT vs INPUT VOLTAGE Output Not Under Test at 0 V TA = 25°C The state of the sta

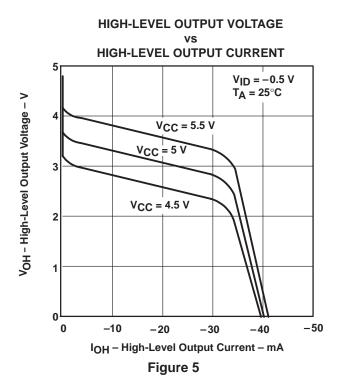
V_I – Input Voltage – V Figure 2

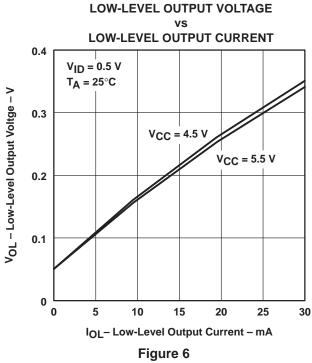


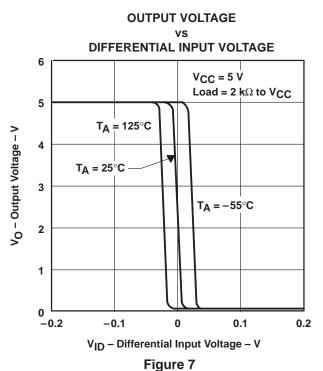
[†] Data for temperatures below 0°C and above 70°C and for supply voltages below 4.75 V and above 5.25 V are applicable to SN55115 circuits only. These parameters were measured with the active pullup connected to the sink output.



TYPICAL CHARACTERISTICS







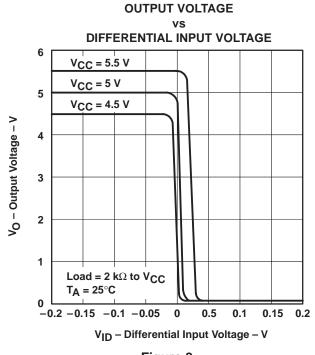
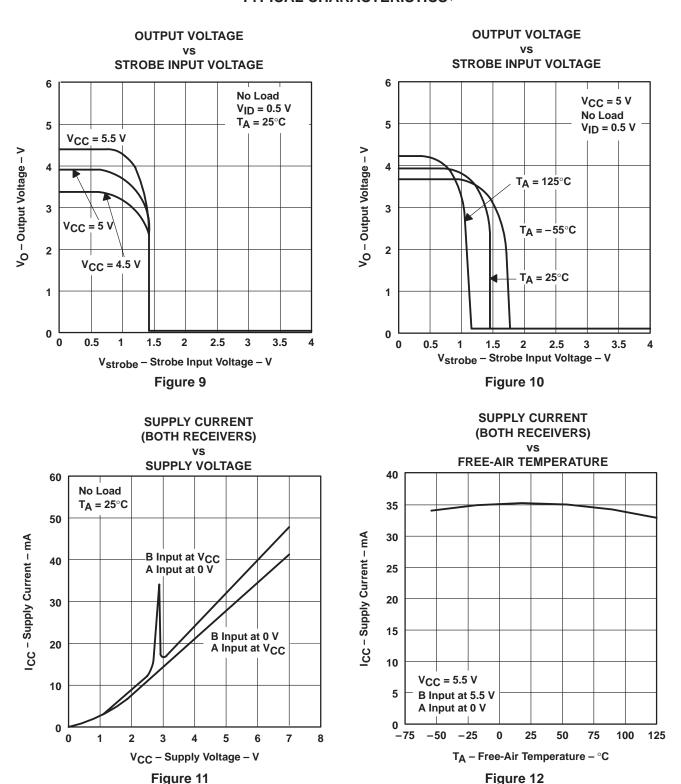


Figure 8

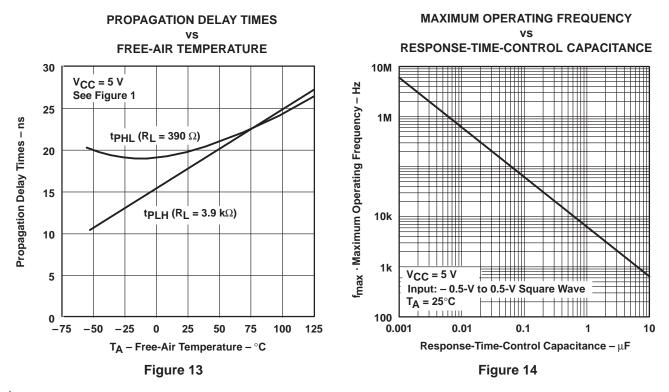
TYPICAL CHARACTERISTICS†



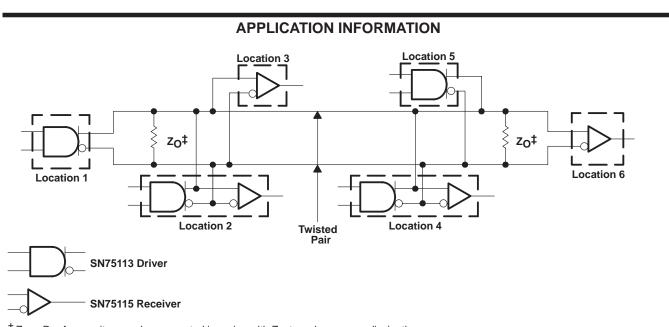
[†] Data for temperatures below 0°C and above 70°C and for supply voltages below 4.75 V and above 5.25 V are applicable to SN55115 circuits only. These parameters were measured with the active pullup connected to the sink output.



TYPICAL CHARACTERISTICS[†]



[†] Data for temperatures below 0°C and above 70°C and for supply voltages below 4.75 V and above 5.25 V are applicable to SN55115 circuits only. These parameters were measured with the active pullup connected to the sink output.



 \ddagger Z_O = R_T. A capacitor may be connected in series with Z_O to reduce power dissipation.

Figure 15. Basic Party-Line or Data-Bus Differential Data Transmission



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PACKAGING INFORMATION

Orderabl	e Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-887	745012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-887	45012A-T	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-887	74501FA	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/1	10404BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN55	115J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN75	115D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN751	15DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN751	15DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN751	15DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7511	5DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7511	5DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75	115N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN751	15NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN751	15NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75118	5NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75115	5NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ55	115FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ5	5115J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ55	5115W	ACTIVE	CFP	W	16	1	TBD	A42 SNPB	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

18-Sep-2008

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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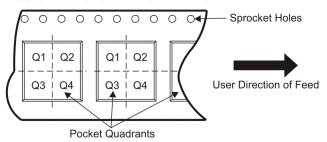
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

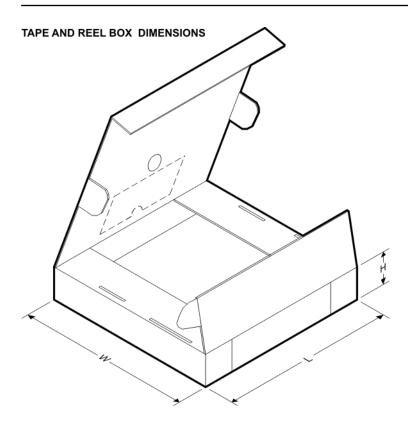
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75115DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75115NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75115DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75115NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



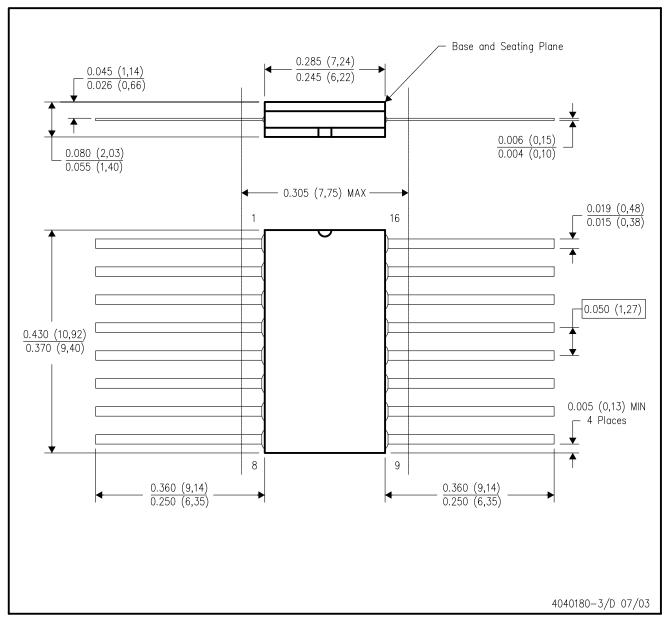
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

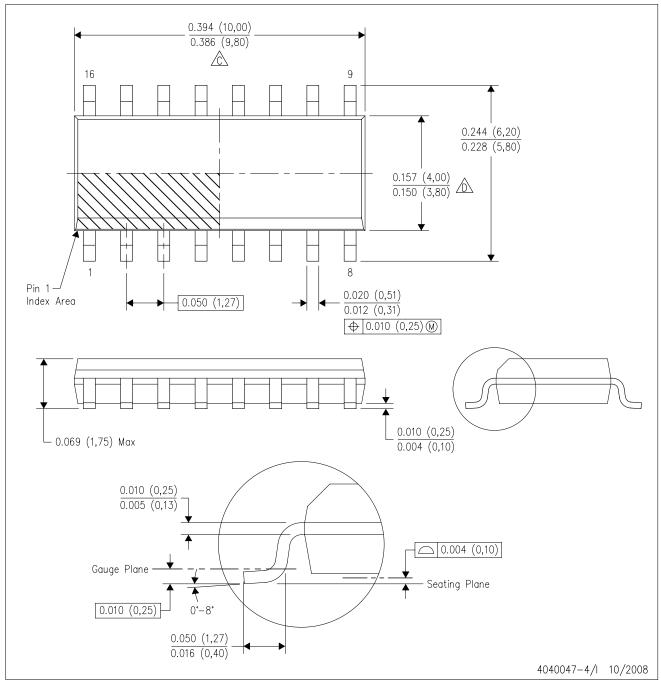


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



D (R-PDS0-G16)

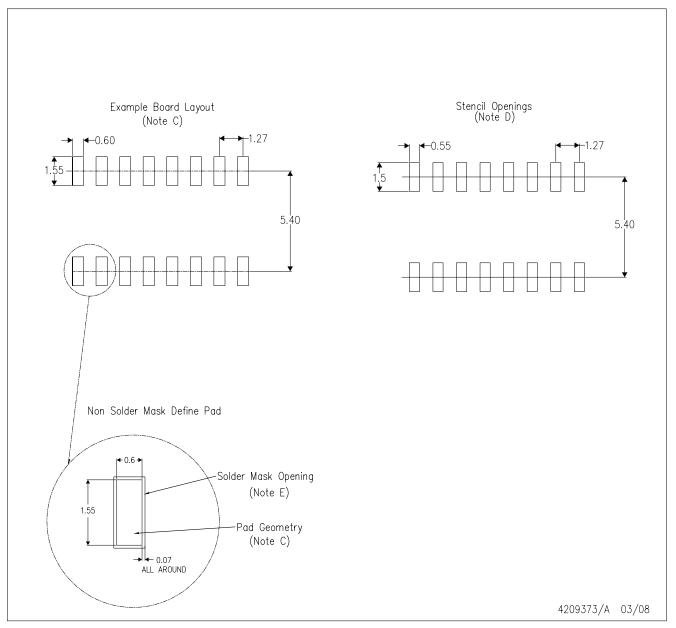
PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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